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Understanding [Embedded - Microprocessors](#)

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of [Embedded - Microprocessors](#)

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details

Product Status	Obsolete
Core Processor	MIPS-II
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	100MHz
Co-Processors/DSP	-
RAM Controllers	SDRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	-
SATA	-
USB	-
Voltage - I/O	3.3V
Operating Temperature	0°C ~ 70°C (TA)
Security Features	-
Package / Case	256-BBGA
Supplier Device Package	256-PBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/idt79rc32v334-100bb

◆ 4 DMA Channels

- 4 general purpose DMA, each with endianness swappers and byte lane data alignment
- Supports scatter/gather, chaining via linked lists of records
- Supports memory-to-memory, memory-to-I/O, memory-to-PCI, PCI-to-PCI, and I/O-to-I/O transfers
- Supports unaligned transfers
- Supports burst transfers
- Programmable DMA bus transactions burst size (up to 16 bytes)

◆ PCI Bus Interface

- 32-bit PCI, up to 66 MHz
- Revision 2.2 compatible
- Target or master
- Host or satellite
- Three slot PCI arbiter
- Serial EEPROM support, for loading configuration registers

◆ Off-the-shelf development tools

◆ JTAG Interface (IEEE Std. 1149.1 compatible)

◆ 256-ball BGA (1.0mm spacing)

◆ 3.3V operation with 5V tolerant I/O

◆ EJTAG in-circuit emulator interface

Device Overview

The IDT RC32334 device is an integrated processor based on the RC32300 CPU core. This product incorporates a high-performance, low-cost 32-bit CPU core with functionality common to a large number of embedded applications. The RC32334 integrates these functions to enable the use of low-cost PC commodity market memory and I/O devices, allowing the aggressive price/performance characteristics of the CPU to be realized quickly into low-cost systems.

CPU Execution Core

The RC32334 integrates the RISCORE32300, the same CPU core found in the award-winning RC32364 microprocessor.

The RISCORE32300 implements the Enhanced MIPS-II ISA. Thus, it is upwardly compatible with applications written for a wide variety of MIPS architecture processors, and it is kernel compatible with the modern operating systems that support IDT's 64-bit RISCController product family.

The RISCORE32300 was explicitly defined and designed for integrated processor products such as the RC32334. Key attributes of the execution core found within this product include:

- ◆ High-speed, 5-stage scalar pipeline executes to 150MHz. This high performance enables the RC32334 to perform a variety of performance intensive tasks, such as routing, DSP algorithms, etc.
- ◆ 32-bit architecture with enhancements of key capabilities. Thus, the RC32334 can execute existing 32-bit programs, while enabling designers to take advantage of recent advances in CPU architecture.
- ◆ Count leading-zeroes/ones. These instructions are common to a wide variety of tasks, including modem emulation, voice over IP compression and decompression, etc.
- ◆ Cache PREFetch instruction support, including a specialized form intended to help memory coherency. System programmers can allocate and stage the use of memory bandwidth to achieve maximum performance.
- ◆ 8kB of 2-way set associative instruction cache

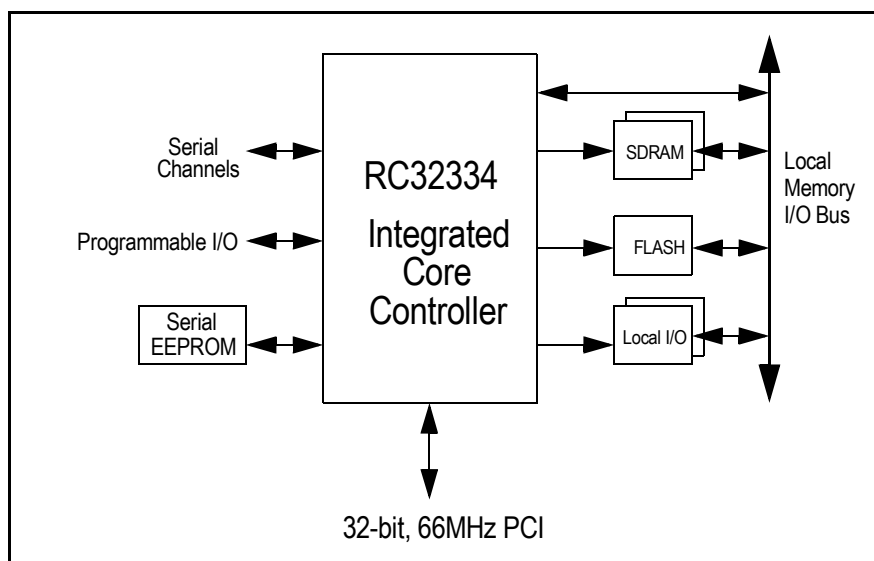


Figure 2 RC32334 Based System Diagram

- ◆ 2KB of 2-way set associative data cache, capable of write-back and write-through operation.
- ◆ Cache locking per line to speed real-time systems and critical system functions
- ◆ On-chip TLB to enable multi-tasking in modern operating systems
- ◆ EJTAG interface to enable sophisticated low-cost in-circuit emulation.

Synchronous-DRAM Interface

The RC32334 integrates a SDRAM controller which provides direct control of system SyncDRAM running at speeds to 75MHz.

Key capabilities of the SDRAM controller include:

- ◆ Direct control of 4 banks of SDRAM (up to 2 64-bit wide DIMMs)
- ◆ On-chip page comparators optimize access latency.
- ◆ Speeds to 75MHz
- ◆ Programmable address map.
- ◆ Supports 16, 64, 128, 256, or 512Mb SDRAM devices
- ◆ Automatic refresh generation driven by on-chip timer
- ◆ Support for discrete devices, SODIMM, or DIMM modules.

Thus, systems can take advantage of the full range of commodity memory that is available, enabling system optimization for cost, real-estate, or other attributes.

Local Memory and I/O Controller

The local memory and I/O controller implements direct control of external memory devices, including the boot ROM as well as other memory areas, and also implements direct control of external peripherals.

The local memory controller is highly flexible, allowing a wide range of devices to be directly controlled by the RC32334 processor. For example, a system can be built using an 8-bit boot ROM, 16-bit FLASH cards (possibly on PCMCIA), a 32-bit SRAM or dual-port memory, and a variety of low-cost peripherals.

Key capabilities include:

- ◆ Direct control of EPROM, FLASH, RAM, and dual-port memories
- ◆ 6 chip-select outputs, supporting up to 64MB per memory space
- ◆ Supports mixture of 8-, 16-, and 32-bit wide memory regions
- ◆ Flexible timing protocols allow direct control of a wide variety of devices
- ◆ Programmable address map for 2 chip selects
- ◆ Automatic wait state generation.

PCI Bus Bridge

In order to leverage the wide availability of low-cost peripherals for the PC market as well as to simplify the design of add-in functions, the RC32334 integrates a full 32-bit PCI bus bridge. Key attributes of this bridge include:

- ◆ 66 MHz operation
- ◆ PCI revision 2.2 compliant
- ◆ Programmable address mappings between CPU/Local memory and PCI memory and I/O
- ◆ On-chip PCI arbiter
- ◆ Extensive buffering allows PCI to operate concurrently with local memory transfers
- ◆ Selectable byte-ordering swapper
- ◆ 5V tolerant I/O.

On-Chip DMA Controller

To minimize CPU exception handling and maximize the efficiency of system bandwidth, the RC32334 integrates a very sophisticated 4-channel DMA controller on chip.

The RC32334 DMA controller is capable of:

- ◆ Chaining and scatter/gather support through the use of a flexible, linked list of DMA transaction descriptors
- ◆ Capable of memory<->memory, memory<->I/O, and PCI<->memory DMA
- ◆ Unaligned transfer support
- ◆ Byte, halfword, word, quadword DMA support.

On-Chip Peripherals

The RC32334 also integrates peripherals that are common to a wide variety of embedded systems.

- ◆ Dual channel 16550 compatible UARTs, with modem control interface on one channel.
- ◆ SPI master mode interface for direct interface to EEPROM, A/D, etc.
- ◆ Interrupt Controller to speed interrupt decode and management
- ◆ Four 32-bit on-chip Timer/Counters
- ◆ Programmable I/O module

Debug Support

To facilitate rapid time to market, the RC32334 provides extensive support for system debug.

First and foremost, this product integrates an EJTAG in-circuit emulation module, allowing a low-cost emulator to interoperate with programs executing on the controller. By using an augmented JTAG interface, the RC32334 is able to reuse the same low-cost emulators developed around the RC32364 CPU.

Secondly, the RC32334 implements additional reporting signals intended to simplify the task of system debugging when using a logic analyzer. This product allows the logic analyzer to differentiate transactions initiated by DMA from those initiated by the CPU and further allows CPU transactions to be sorted into instruction fetches vs. data fetches.

Finally, the RC32334 implements a full boundary scan capability, allowing board manufacturing diagnostics and debug.

Packaging

The RC32334 is packaged using a 256-lead PBGA package, with 1.0mm ball spacing.

Thermal Considerations

The RC32334 consumes less than 2.1 W peak power. The device is guaranteed in an ambient temperature range of 0° to +70° C for commercial temperature devices; -40° to +85° for industrial temperature devices.

Revision History

May 16, 2000: Initial version.

June 8, 2000: In CPU Core Specific Signals section of Table 1, changed `cpu_dr_r_n` pin from Input to Output. Updated document from Advance to Preliminary Information.

June 15, 2000: In Table 1, switched assertion and de-assertion for `debug_cpu_dma_n` signal. In the AC Timing Characteristics table, added SPI section and adjusted parameters in the Reset section.

July 12, 2000: Removed "Preliminary Information" statement. Added information regarding external pull-ups and pull-downs to the Pin Description Table. Made minor revisions in other parts of the data sheet.

August 3, 2000: Added Pin Layout diagram showing power and ground pins. Revised Power Curves section to reflect support of only 2x, 3x, and 4x.

August 30, 2000: Added Standby mode and values to Power Consumption table. Extended Power Curve figure to 75 MHz.

September 25, 2000: Changed MIPS32 ISA to Enhanced MIPS-II. In Local System Interface section of Table 6, changed `Thld2` values for `mem_data[31:0]` from 1.8 to 1.5 ns and changed `Tdoh3` values for `mem_addr[25:2]`, etc. from 1.8 to 1.5 ns.

December 12, 2000: Changed Max values for `cpu_masterclock` period in Table 5 and added footnote. In Table 1, added 2nd alternate function for `spi_mosi`, `spi_miso`, `spi_sck`. In Table 10, removed the "1" from Alt column for `cpu_masterclk` and added "2" in Alt column for pins G3, G4, H2. In RC32334 Alternate Signal Functions table: added pin T2; added pin names in Alt #2 column for pins G3, G4, H2; added `PIO[11]` to Alt #2 column for pin R3.

January 4, 2001: In Table 6 under Interrupt Handling, moved the values for `Tsu9` from the Max to the Min columns.

March 13, 2001: Changed upper ambient temperature for industrial and commercial uses from +70° C to +85° C.

June 7, 2001: In the Clock Parameters table, added footnote 3 to `output_clk` category and added NA to Min and Max columns. In Figure 3 (Reset Specification), enhanced signal line for `cpu_masterclk`. In Local System Interface section of AC Timing Characteristics table, changed values in Min column for last category of signals (`Tdoh3`) from 1.5 to 2.5 for all speeds. In SDRAM Controller section of same table, changed values in Min column for last category of signals (9 signals) from 1 to 2.5 for all speeds.

September 14, 2001: In the Reset category of Table 6: switched `mem_addr[19:17]` from `Tsu22` and `Thld22` to `Tsu10` and `Thld10`; switched `mem_addr[22:20]` from `Tsu10` and `Thld10` to `Tsu22` and `Thld22`; moved `eitag_pcst[2:0]` from Reset to Debug Interface category under `Tsu20` and `Thld20`.

November 1, 2001: Added Input Voltage Undershoot parameter and 2 footnotes to Table 10.

March 20, 2002: In Local System Interface section of AC Timing Characteristics table, changed values in Min column for last category of signals (`Tdoh3`) from 2.5 to 1.5 for all speeds. In Table 8, PCI Drive Output Pads, the Conditions for parameters V_{OL} , V_{OH} , V_{IL} , and V_{IH} were changed to read Per PCI 2.2.

May 2, 2002: Changed upper ambient temperature for commercial uses back from +85° C to +70° C (changed erroneously from 70 to 85 on March 13, 2001). Added Reset State Status column to Table 1. Revised description of `jtag_trst_n` in Table 1 and changed this pin to a pull-down instead of a pull-up.

July 3, 2002: This data sheet now describes revision Y silicon and is no longer applicable to revision Z.

July 12, 2002: In Table 6: PCI section, changed `Thld` Min values from 1 to zero; DMA section, changed `Thld9` Min values from 2 to 1; in PIO section, changed `Thld9` Min values from 2 to 1; in Timer section, changed `Thld10` Min values from 2 to 1. Revision Y data sheet changed from Preliminary to Final.

September 18, 2002: Added `cpu_coldreset_n` rise time to Table 5, Clock Parameters. Added `mem_addr[16]` and `sdram_addr[16]` to Tables 1 and 12. Changed Logic Diagram to include `sdram_addr[16]`.

December 18, 2002: In the Reset section of Table 6, AC Timing Characteristics, setup and hold time categories for `cpu_coldreset_n` have been deleted.

July 30, 2003: In Table 8, added 3 new categories (Input Pads, PCI Input Pads, and All Pads) and added footnotes 2 and 3.

March 24, 2004: In Table 1, changed description in Satellite Mode for `pci_rst_n`. Specified "cold" reset on pages 11 and 12. Changed the maximum value for V_{cc} to 4.0 in Table 10, Absolute Maximum Ratings, and changed footnote 1 to that table. Added Power Ramp-up section on page 21.

August 31, 2004: Added "Green" orderable parts on page 30.

Pin Description Table

The following table lists the pins provided on the RC32334. Note that those pin names followed by "_n" are active-low signals. All external pull-ups and pull-downs require 10 k Ω resistor.

Name	Type	Reset State Status	Drive Strength Capability	Description																									
Local System Interface																													
mem_data[31:0]	I/O	Z	High	Local System Data Bus Primary data bus for memory. I/O and SDRAM.																									
mem_addr[25:2]	I/O	[25:10] Z [9:2] L	[25:17] Low [16:2] High	Memory Address Bus These signals provide the Memory or DRAM address, during a Memory or DRAM bus transaction. During each word data, the address increments either in linear or sub-block ordering, depending on the transaction type. The table below indicates how the memory write enable signals are used to address discreet memory port width types. <table border="1"> <thead> <tr> <th>Port Width</th><th>Pin Signals mem_we_n[3]</th><th>mem_we_n[2]</th><th>mem_we_n[1]</th><th>mem_we_n[0]</th></tr> </thead> <tbody> <tr> <td>DMA (32-bit)</td><td>mem_we_n[3]</td><td>mem_we_n[2]</td><td>mem_we_n[1]</td><td>mem_we_n[0]</td></tr> <tr> <td>32-bit</td><td>mem_we_n[3]</td><td>mem_we_n[2]</td><td>mem_we_n[1]</td><td>mem_we_n[0]</td></tr> <tr> <td>16-bit</td><td>Byte High Write Enable</td><td>mem_addr[1]</td><td>Not Used (Driven Low)</td><td>Byte Low Write Enable</td></tr> <tr> <td>8-bit</td><td>Not Used (Driven High)</td><td>mem_addr[1]</td><td>mem_addr[0]</td><td>Byte Write Enable</td></tr> </tbody> </table> mem_addr[22] Alternate function: reset_boot_mode[1]. mem_addr[21] Alternate function: reset_boot_mode[0]. mem_addr[20] Alternate function: reset_pci_host_mode. mem_addr[19] Alternate function: modebit [9]. mem_addr[18] Alternate function: modebit [8]. mem_addr[17] Alternate function: modebit [7]. mem_addr[16] Alternate function: sdram_addr[16]. mem_addr[15] Alternate function: sdram_addr[15]. mem_addr[14] Alternate function: sdram_addr[14]. mem_addr[13] Alternate function: sdram_addr[13]. mem_addr[11] Alternate function: sdram_addr[11]. mem_addr[10] Alternate function: sdram_addr[10]. mem_addr[9] Alternate function: sdram_addr[9]. mem_addr[8] Alternate function: sdram_addr[8]. mem_addr[7] Alternate function: sdram_addr[7]. mem_addr[6] Alternate function: sdram_addr[6]. mem_addr[5] Alternate function: sdram_addr[5]. mem_addr[4] Alternate function: sdram_addr[4]. mem_addr[3] Alternate function: sdram_addr[3]. mem_addr[2] Alternate function: sdram_addr[2].	Port Width	Pin Signals mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]	DMA (32-bit)	mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]	32-bit	mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]	16-bit	Byte High Write Enable	mem_addr[1]	Not Used (Driven Low)	Byte Low Write Enable	8-bit	Not Used (Driven High)	mem_addr[1]	mem_addr[0]	Byte Write Enable
Port Width	Pin Signals mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]																									
DMA (32-bit)	mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]																									
32-bit	mem_we_n[3]	mem_we_n[2]	mem_we_n[1]	mem_we_n[0]																									
16-bit	Byte High Write Enable	mem_addr[1]	Not Used (Driven Low)	Byte Low Write Enable																									
8-bit	Not Used (Driven High)	mem_addr[1]	mem_addr[0]	Byte Write Enable																									
mem_cs_n[5:0]	Output	H	Low with internal pull-up	Memory Chip Select Negated Recommend external pull-up. Signals that a Memory Bank is actively selected.																									
mem_oe_n	Output	H	High	Memory Output Enable Negated Recommend external pull-up. Signals that a Memory Bank can output its data lines onto the cpu_ad bus.																									

Table 1 Pin Description (Part 1 of 7)

Name	Type	Reset State Status	Drive Strength Capability	Description
sdram_cas_n	Output	H	High	SDRAM CAS Negated SDRAM mode: Provides SDRAM CAS control signal to all SDRAM banks.
sdram_we_n	Output	H	High	SDRAM WE Negated SDRAM mode: Provides SDRAM WE control signal to all SDRAM banks.
sdram_cke	Output	H	High	SDRAM Clock Enable SDRAM mode: Provides clock enable to all SDRAM banks.
sdram_cs_n[3:0]	Output	H	High	SDRAM Chip Select Negated Bus Recommend external pull-up. SDRAM mode: Provides chip select to each SDRAM bank. SODIMM mode: Provides upper select byte enables [7:4].
sdram_s_n[1:0]	Output	H	High	SDRAM SODIMM Select Negated Bus SDRAM mode: Not used. SDRAM SODIMM mode: Upper and lower chip selects.
sdram_bemask_n [3:0]	Output	H	High	SDRAM Byte Enable Mask Negated Bus (DQM) SDRAM mode: Provides byte enables for each byte lane of all DRAM banks. SODIMM mode: Provides lower select byte enables [3:0].
sdram_245_oe_n	Output	H	Low	SDRAM FCT245 Output Enable Negated Recommend external pull-up. SDRAM mode: Controls output enable to optional FCT245 transceiver bank by asserting during both reads and writes to any DRAM bank.
sdram_245_dt_r_n	Output	Z	High	SDRAM FCT245 Direction Transmit/Receive Recommend external pull-up. Uses cpu_dt_r_n. See CPU Core Specific Signals below.

On-Chip Peripherals

dma_ready_n[1:0] / dma_done_n[1:0]	I/O	Z	Low	DMA Ready Negated Bus Requires external pull-up. Ready mode: Input pin for each general purpose DMA channel that can initiate the next datum in the current DMA descriptor frame. Done mode: Input pin for each general purpose DMA channel that can terminate the current DMA descriptor frame. dma_ready_n[0] 1st Alternate function PIO[1]; 2nd Alternate function: dma_done_n[0]. dma_ready_n[1] 1st Alternate function PIO[0]; 2nd Alternate function: dma_done_n[1].
pio[15:0]	I/O	See related pins	Low	Programmable Input/Output General purpose pins that can each be configured as a general purpose input or general purpose output. These pins are multiplexed with other pin functions: uart_cts_n[0], uart_dsr_n[0], uart_dtr_n[0], uart_rts_n[0], pci_gnt_n[1], spi_mosi, spi_miso, spi_sck, spi_ss_n, uart_rx[0], uart_tx[0], uart_rx[1], uart_tx[1], timer_tc_n[0], dma_ready_n[0], dma_ready_n[1]. Note that pci_gnt_n[1], spi_mosi, spi_sck, and spi_ss_n default to outputs at reset time. The others default to inputs.
timer_tc_n[0] / timer_gate_n[0]	I/O	Z	Low	Timer Terminal Count Overflow Negated Terminal count mode (timer_tc_n): Output indicating that the timer has reached its count compare value and has overflowed back to 0. Gate mode (timer_gate_n): input indicating that the timer may count one tick on the next clock edge. 1st Alternate function: PIO[2]. 2nd Alternate function: timer_gate_n[0].
uart_rx[1:0]	I/O	Z	Low	UART Receive Data Bus UART mode: Each UART channel receives data on their respective input pin. uart_rx[0] Alternate function: PIO[6]. uart_rx[1] Alternate function: PIO[4].

Table 1 Pin Description (Part 4 of 7)

Name	Type	Reset State Status	Drive Strength Capability	Description
uart_tx[1:0]	I/O	Z	Low	UART Transmit Data Bus UART mode: Each UART channel sends data on their respective output pin. Note that these pins default to inputs at reset time and must be programmed via the PIO interface before being used as UART outputs. uart_tx[0] Alternate function: PIO[5]. uart_tx[1] Alternate function: PIO[3].
uart_cts_n[0] uart_dsr_n[0] uart_dtr_n[0] uart_rts_n[0]	I/O	Z	Low	UART Transmit Data Bus UART mode: Data bus modem control signal pins for UART channel 0. uart_cts_n[0] Alternate function: PIO[15]. uart_dsr_n[0] Alternate function: PIO[14]. uart_dtr_n[0] Alternate function: PIO[13]. uart_rts_n[0] Alternate function: PIO[12].
spi_mosi	I/O	L	Low	SPI Data Output Serial mode: Output pin from RC32334 as an Input to a Serial Chip for the Serial data input stream. In PCI satellite mode, acts as an Output pin from RC32334 that connects as an Input to a Serial Chip for the Serial data input stream for loading PCI Configuration Registers in the RC32334 Reset Initialization Vector PCI boot mode. 1st Alternate function: PIO[10]. Defaults to the output direction at reset time. 2nd Alternate function: pci_eeprom_mdo.
spi_miso	I/O	Z	Low	SPI Data Input Serial mode: Input pin to RC32334 from the Output of a Serial Chip for the Serial data output stream. In PCI satellite mode, acts as an Input pin from RC32334 that connects as an output to a Serial Chip for the Serial data output stream for loading PCI Configuration Registers in the RC32334 Reset Initialization Vector PCI boot mode. Defaults to input direction at reset time. 1st Alternate function: PIO[7]. 2nd Alternate function: pci_eeprom_mdi.
spi_sck	I/O	L	Low	SPI Clock Serial mode: Output pin for Serial Clock. In PCI satellite mode, acts as an Output pin for Serial Clock for loading PCI Configuration Registers in the RC32334 Reset Initialization Vector PCI boot mode. 1st Alternate function: PIO[9]. Defaults to the output direction at reset time. 2nd Alternate function: pci_eeprom_sk.
spi_ss_n	I/O	H	Low	SPI Chip Select Output pin selecting the serial protocol device as opposed to the PCI satellite mode EEPROM device. Alternate function: PIO[8]. Defaults to the output direction at reset time.

CPU Core Specific Signals

cpu_nmi_n	Input		—	CPU Non-Maskable Interrupt Requires external pull-up. This interrupt input is active low to the CPU.
cpu_masterclk	Input		—	CPU Master System Clock Provides the basic system clock.
cpu_int_n[5:4], [2:0]	Input		—	CPU Interrupt Requires external pull-up. These interrupt inputs are active low to the CPU.
cpu_coldreset_n	Input	L	—	CPU Cold Reset This active-low signal is asserted to the RC32334 after V_{cc} becomes valid on the initial power-up. The Reset initialization vectors for the RC32334 are latched by cold reset.

Table 1 Pin Description (Part 5 of 7)

Name	Type	Reset State Status	Drive Strength Capability	Description
cpu_dt_r_n	Output	Z	—	CPU Direction Transmit/Receive This active-low signal controls the DT/R pin of an optional FCT245 transceiver bank. It is asserted during read operations. 1st Alternate function: mem_245_dt_r_n. 2nd Alternate function: sdram_245_dt_r_n.

JTAG Interface Signals

jtag_tck	Input		—	JTAG Test Clock Requires external pull-down. An input test clock used to shift into or out of the Boundary-Scan register cells. jtag_tck is independent of the system and the processor clock with nominal 50% duty cycle.
jtag_tdi, ejtag_dint_n	Input		—	JTAG Test Data In Requires an external pull-up on the board. On the rising edge of jtag_tck, serial input data are shifted into either the Instruction or Data register, depending on the TAP controller state. During Real Mode, this input is used as an interrupt line to stop the debug unit from Real Time mode and return the debug unit back to Run Time Mode (standard JTAG). This pin is also used as the ejtag_dint_n signal in the EJTAG mode.
jtag_tdo, ejtag_tpc	Output	Z	High	JTAG Test Data Out The jtag_tdo is serial data shifted out from instruction or data register on the falling edge of jtag_tck. When no data is shifted out, the jtag_tdo is tri-stated. During Real Time Mode, this signal provides a non-sequential program counter at the processor clock or at a division of processor clock. This pin is also used as the ejtag_tpc signal in the EJTAG mode.
jtag_tms	Input		—	JTAG Test Mode Select Requires external pull-up. The logic signal received at the jtag_tms input is decoded by the TAP controller to control test operation. jtag_tms is sampled on the rising edge of the jtag_tck.
jtag_trst_n	Input	L	—	JTAG Test Reset When neither JTAG nor EJTAG are being used, jtag_trst_n must be driven low (pulled down) or the jtag_tms/ejtag_tms signals must be pulled up and jtag_clk actively clocked.
ejtag_dclk	Output	Z	—	EJTAG Test Clock Processor Clock. During Real Time Mode, this signal is used to capture address and data from the ejtag_tpc signal at the processor clock speed or any division of the internal pipeline.
ejtag_pcst[2:0]	I/O	Z	Low	EJTAG PC Trace Status Information 111 (STL) Pipe line Stall 110 (JMP) Branch/Jump forms with PC output 101 (BRT) Branch/Jump forms with no PC output 100 (EXP) Exception generated with an exception vector code output 011 (SEQ) Sequential performance 010 (TST) Trace is outputted at pipeline stall time 001 (TSQ) Trace trigger output at performance time 000 (DBM) Run Debug Mode Alternate function: modebit[2:0].
ejtag_debugboot	Input		— Requires external pull-down	EJTAG DebugBoot The ejtag_debugboot input is used during reset and forces the CPU core to take a debug exception at the end of the reset sequence instead of a reset exception. This enables the CPU to boot from the ICE probe without having the external memory working. This input signal is level sensitive and is not latched internally. This signal will also set the JtagBrk bit in the JTAG_Control_Register[12].
ejtag_tms	Input		— Requires external pull-up	EJTAG Test Mode Select An external pull-up on the board is required. The ejtag_tms is sampled on the rising edge of jtag_tck.

Table 1 Pin Description (Part 6 of 7)

Name	Type	Reset State Status	Drive Strength Capability	Description
Debug Signals				
debug_cpu_dma_n	I/O	Z	Low	Debug CPU versus DMA Negated De-assertion high during debug_cpu_ads_n assertion or debug_cpu_ack_n assertion indicates transaction was generated from the CPU. Assertion low during debug_cpu_ads_n assertion or debug_cpu_ack_n assertion indicates transaction was generated from DMA. Alternate function: modebit[6].
debug_cpu_ack_n	I/O	Z	Low	Debug CPU Acknowledge Negated Indicates either a data acknowledge to the CPU or DMA. Alternate function: modebit[4].
debug_cpu_ads_n	I/O	Z	Low	Debug CPU Address/Data Strobe Negated Assertion indicates that either a CPU or a DMA transaction is beginning and that the mem_data[31:4] bus has the current block address. Alternate function: modebit[5].
debug_cpu_i_d_n	I/O	Z	Low	Debug CPU Instruction versus Data Negated Assertion during debug_cpu_ads_n assertion or debug_cpu_ack_n assertion indicates transaction is a CPU or DMA data transaction. De-assertion during debug_cpu_ads_n assertion or debug_cpu_ack_n assertion indicates transaction is a CPU instruction transaction. Alternate function: modebit[3].

Table 1 Pin Description (Part 7 of 7)

Mode Bit Settings to Configure Controller on Reset

The following table lists the mode bit settings to configure the controller on cold reset.

Pin	Mode Bit	Description	Value	Mode Setting
ejtag_pcst[2:0]	2:0 MSB (2)	Clock Multiplier MasterClock is multiplied internally to generate PClock	0	Multiply by 2
			1	Multiply by 3
			2	Multiply by 4
			3	Reserved
			4	Reserved
			5	Reserved
			6	Reserved
			7	Reserved
debug_cpu_i_d_n	3	EndBit	0	Little-endian ordering
			1	Big-endian ordering
debug_cpu_ack_n	4	Reserved	0	
debug_cpu_ads_n	5	Reserved	0	
debug_cpu_dma_n	6	TmrIntEn Enables/Disables the timer interrupt on Int*[5]	0	Enables timer interrupt
			1	Disables timer interrupt
mem_addr[17]	7	Reserved for future use	1	

Table 2 Boot-Mode Configuration Settings (Part 1 of 2)

Pin	Mode Bit	Description	Value	Mode Setting
mem_addr[19:18]	9:8 MSB (9)	Boot-Prom Width specifies the memory port width of the memory space which contains the boot prom.	00	8 bits
			01	16 bits
			10	32 bits
			11	Reserved

Table 2 Boot-Mode Configuration Settings (Part 2 of 2)

reset_boot_mode Settings

By using the non-boot mode cold reset initialization mode the user can change the internal register addresses from base 1800_0000 to base 1900_0000, as required. The RC32334 cold reset-boot mode initialization setting values and mode descriptions are listed below.

Pin	Reset Boot Mode	Description	Value	Mode Settings
mem_addr[22:21]	1:0 MSB (1)	Tri-state memory bus and EEPROM bus during cold reset_n assertion	11	Tri-state_bus_mode
		Reserved	10	
		PCI-boot mode (pci_host_mode must be in satellite mode) RC32334 will reset either from a cold reset or from a PCI reset. Boot code is provided via PCI.	01	PCI_boot_mode
		Standard-boot mode Boot from the RC32334's memory controller (typical system).	00	standard_boot_mode

Table 3 RC32334 reset_boot_mode Initialization Settings

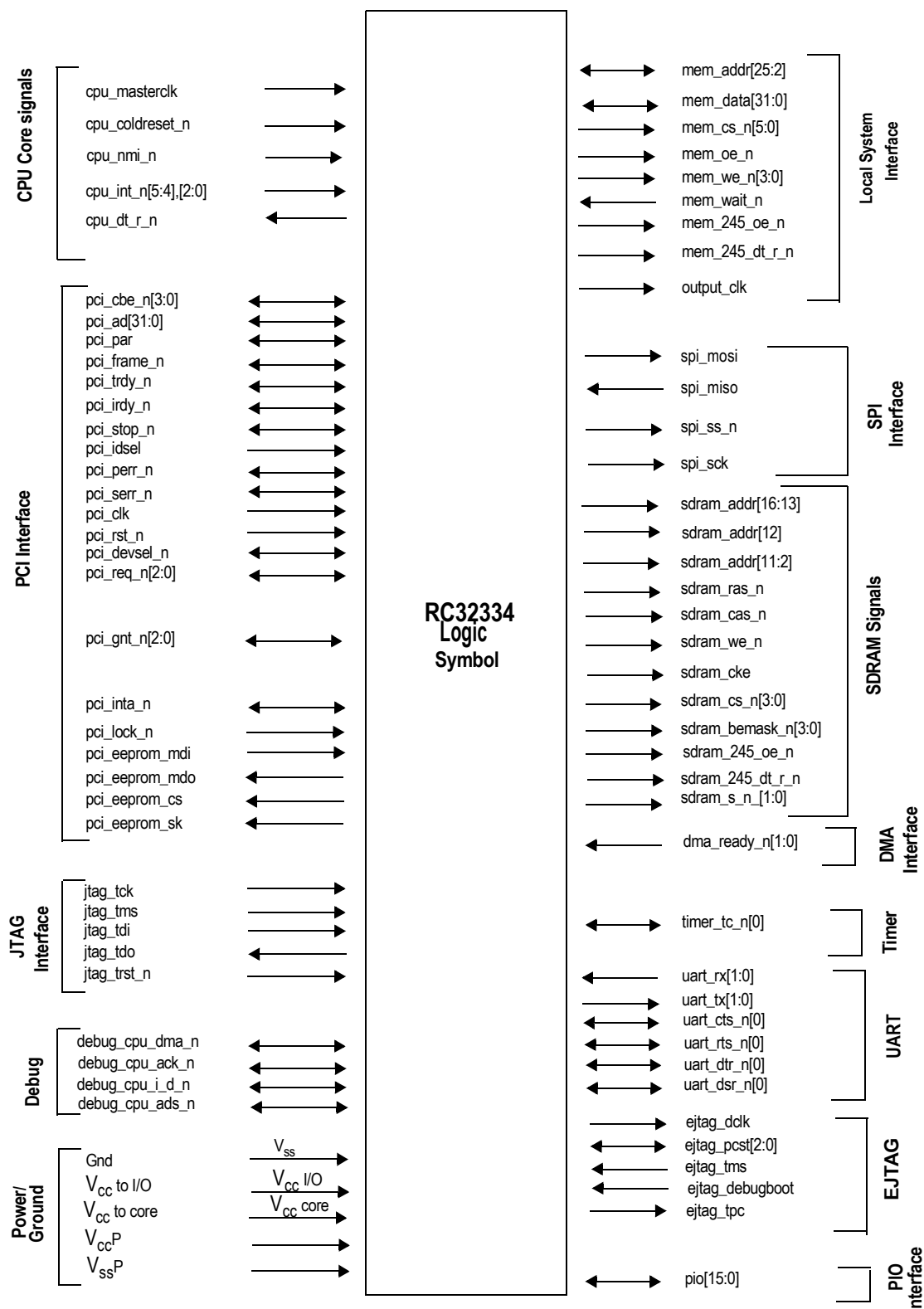
pci_host_mode Settings

During cold reset initialization, the RC32334's PCI interface can be set to the Satellite or Host mode settings. When set to the Host mode, the CPU must configure the RC32334's PCI configuration registers, including the read-only registers. If the RC32334's PCI is in the PCI-boot mode Satellite mode, read-only configuration registers are loaded by the serial EEPROM.

Pin	Reset Boot Mode	Description	Value	Mode Settings
mem_addr[20]	PCI host mode	PCI is in satellite mode	1	PCI_satellite
		PCI is in host mode (typical system)	0	PCI_host

Table 4 RC32334 pci_host_mode Initialization Settings

Logic Diagram — RC32334



Clock Parameters — RC32334

(Ta = 0°C to +70°C Commercial, Ta = -40°C to +85°C Industrial, V_{cc} I/O = +3.3V±5%, V_{cc} Core = +3.3V±5%)

Parameter	Symbol	Test Conditions	RC32334 100MHz		RC32334 133MHz		RC32334 150MHz		Units
			Min	Max	Min	Max	Min	Max	
cpu_masterclock HIGH	t _{MCHIGH}	Transition ≤ 2ns	8	—	6.75	—	6	—	ns
cpu_masterclock LOW	t _{MCLOW}	Transition ≤ 2ns	8	—	6.75	—	6	—	ns
cpu_masterclock period ¹	t _{MCP}	—	20	66.6	15	66.6	13.33	66.6	ns
cpu_masterclock Rise & Fall Time ²	t _{MCRise} , t _{MCFall}	—	—	3	—	3	—	3	ns
cpu_masterclock Jitter	t _{JITTER}	—	—	± 250	—	± 250	—	± 200	ps
pci_clk Rise & Fall Time	t _{PCRise} , t _{PCFall}	PCI 2.2	—	1.6	—	1.6	—	1.6	ns
pci_clk Period ¹	t _{PCP}	—	15	—	15	—	15	—	ns
jtag_tck Rise & Fall Time	t _{JCRise} , t _{JCFall}	—	—	5	—	5	—	5	ns
ejtag_dck period	t _{DCK} , t _{t1}	—	10	—	10	—	10	—	ns
jtag_tck clock period	t _{TCK} , t ₃	—	100	—	100	—	100	—	ns
ejtag_dck High, Low Time	t _{DCK High} , t ₉ t _{DCK Low} , t ₁₀	—	4	—	4	—	4	—	ns
ejtag_dck Rise, Fall Time	t _{DCK Rise} , t ₉ t _{DCK Fall} , t ₁₀	—	—	1	—	1	—	1	ns
output_clk ³	Tdo21	—	N/A	N/A	N/A	N/A	N/A	N/A	—
cpu_coldreset_n Asserted during power-up		power-on sequence	120	—	120	—	120	—	ms
cpu_coldreset_n Rise Time	t _{CRRise}	—	—	5	—	5	—	5	ns

Table 5 Clock Parameters - RC32334

¹ cpu_masterclock frequency should never be below pci_clk frequency if PCI interface is used.

² Rise and fall times are measured between 10% and 90%

³ Output_clk should not be used in a system. Only the cpu_masterclock or its derivative must be used to drive all the subsystems with designs based on the RC32334 device. Refer to the RC3233x Device Errata for more information.

Reset Specification

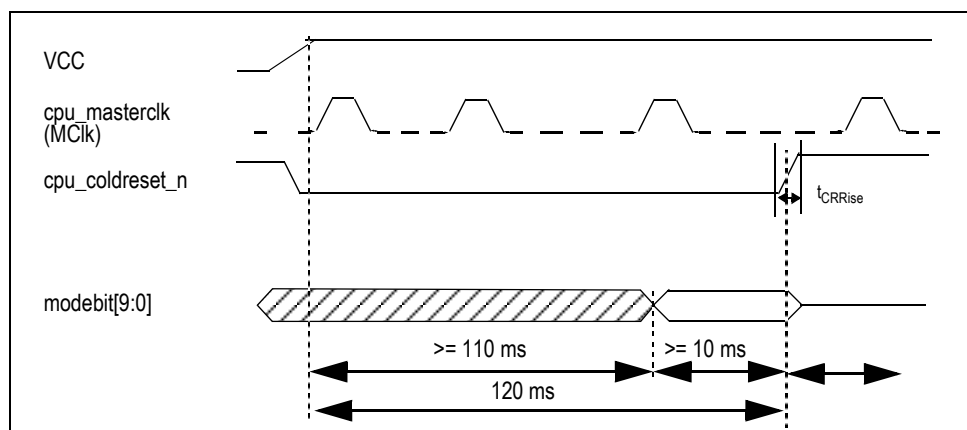


Figure 3 Mode Configuration Interface Cold Reset Sequence

Power Ramp-up

There is no special requirement for how fast Vcc and VccP ramp up to 3.3V. However, all timing references are based on Vcc and VccP stabilized at 3.3V -5%.

AC Timing Characteristics — RC32334

(Ta = 0°C to +70°C Commercial, Ta = -40°C to +85°C Industrial, V_{cc} I/O = +3.3V±5%, V_{cc} Core = +3.3V±5%)

Signal	Symbol	Reference Edge	RC32334 ¹ 100MHz		RC32334 ¹ 133MHz		RC32334 ¹ 150MHz		Unit	User Manual Timing Diagram Reference
			Min	Max	Min	Max	Min	Max		

Local System Interface

mem_data[31:0] (data phase)	Tsu2	cpu_masterclk rising	6	—	5	—	4.8	—	ns	Chapter 9, Figures 9.2 and 9.3
mem_data[31:0] (data phase)	Thld2	cpu_masterclk rising	1.5	—	1.5	—	1.5	—	ns	
cpu_dt_r_n	Tdo3	cpu_masterclk rising	—	15	—	12	—	10	ns	
mem_data[31:0]	Tdo4	cpu_masterclk rising	—	12	—	10	—	9.3	ns	
mem_data[31:0] output hold time	Tdoh1	cpu_masterclk rising	1	—	1	—	1	—	ns	
mem_data[31:0] (tristate disable time)	Tdz	cpu_masterclk rising	—	12 ²	—	10 ²	—	9.3 ²	ns	
mem_data[31:0] (tristate to data time)	Tzd	cpu_masterclk rising	—	12 ²	—	10 ²	—	9.3 ²	ns	
mem_wait_n	Tsu6	cpu_masterclk rising	9	—	7	—	6	—	ns	Chapter 10, Figures 10.6 through 10.8
mem_wait_n	Thld8	cpu_masterclk rising	1	—	1	—	1	—	ns	
mem_addr[25:2]	Tdo5	cpu_masterclk rising	—	12	—	9	—	8	ns	
mem_cs_n[5:0]	Tdo6	cpu_masterclk rising	—	12	—	9	—	8	ns	
mem_oe_n, mem_245_oe_n	Tdo7	cpu_masterclk rising	—	12	—	9	—	8	ns	
mem_we_n[3:0]	Tdo7a	cpu_masterclk rising	—	15	—	12	—	10	ns	
mem_245_dt_r_n	Tdo8	cpu_masterclk rising	—	15	—	12	—	10	ns	
mem_addr[25:2] mem_cs_n[5:0] mem_oe_n, mem_we_n[3:0], mem_245_dt_r_n, mem_245_oe_n	Tdoh3	cpu_masterclk rising	1.5	—	1.5	—	1.5	—	ns	

PCI

pci_ad[31:0], pci_cbe_n[3:0], pci_par, pci_frame_n, pci_trdy_n, pci_irdy_n, pci_stop_n, pci_perr_n, pci_serr_n, pci_devsel_n, pci_lock_n ³	Tsu	pci_clk rising	3	—	3	—	3	—	ns	Per PCI 2.2
pci_idsel, pci_req_n[2], pci_req_n[1], pci_req_n[0], pci_gnt_n[0], pci_inta_n	Tsu	pci_clk rising	5	—	5	—	5	—	ns	
pci_gnt_n[0]	Tsu	pci_clk rising	5	—	5	—	5	—	ns	
pci_ad[31:0], pci_cbe_n[3:0], pci_par, pci_frame_n, pci_trdy_n, pci_irdy_n, pci_stop_n, pci_perr_n, pci_serr_n, pci_rst_n, pci_devsel_n, pci_lock_n ³	Thld	pci_clk rising	0	—	0	—	0	—	ns	
pci_idsel, pci_req_n[2], pci_req_n[1], pci_req_n[0], pci_gnt_n[0], pci_inta_n	Thld	pci_clk rising	0	—	0	—	0	—	ns	
pci_eeprom_mdi	Tsu	pci_clk rising, pci_eeprom_sk falling	15	—	12	—	10	—	ns	

Table 6 AC Timing Characteristics - RC32334 (Part 1 of 4)

Signal	Symbol	Reference Edge	RC32334 ¹ 100MHz		RC32334 ¹ 133MHz		RC32334 ¹ 150MHz		Unit	User Manual Timing Diagram Reference	
			Min	Max	Min	Max	Min	Max			
UARTs											
uart_rx[1:0], uart_tx[1:0], uart_cts_n[0], uart_dsr_n[0], uart_dtr_n[0], uart_rts_n[0]	Tsu7	cpu_masterclk rising	15	—	12	—	10	—	ns	Chapter 17, Figure 17.16	
uart_rx[1:0], uart_tx[1:0], uart_cts_n[0], uart_dsr_n[0], uart_dtr_n[0], uart_rts_n[0]	Thld9	cpu_masterclk rising	15	—	12	—	10	—	ns		
uart_rx[1:0], uart_tx[1:0], uart_cts_n[0], uart_dsr_n[0], uart_dtr_n[0], uart_rts_n[0]	Tdo16	cpu_masterclk rising	—	15	—	12	—	10	ns		
uart_rx[1:0], uart_tx[1:0], uart_cts_n[0], uart_dsr_n[0], uart_dtr_n[0], uart_rts_n[0]	Tdoh8	cpu_masterclk rising	1	—	1	—	1	—	ns		
SPI Interface											
spi_clk, spi_mosi, spi_miso	Tsu7	cpu_masterclk rising	15	—	12	—	10	—	ns	Chapter 18, Figures 18.8 and 18.9	
spi_clk, spi_mosi, spi_miso	Thld9	cpu_masterclk rising	15	—	12	—	10	—	ns		
spi_clk, spi_mosi, spi_miso	Tdo16	cpu_masterclk rising	—	15	—	12	—	10	ns		
spi_clk, spi_mosi, spi_miso	Tdoh8	cpu_masterclk rising	1	—	1	—	1	—	ns		
Reset											
mem_addr[19:17]	Tsu10	cpu_coldreset_n rising	10	—	10	—	10	—	ms	Chapter 19 Figures 19.8 and 19.9	
mem_addr[19:17]	Thld10	cpu_coldreset_n rising	1	—	1	—	1	—	ns		
mem_addr[22:20],	Tsu22	cpu_masterclk rising	9	—	7	—	6	—	ns		
mem_addr[22:20]	Thld22	cpu_masterclk rising	1	—	1	—	1	—	ns		
Debug Interface											
debug_cpu_dma_n, debug_cpu_ack_n, debug_cpu_ads_n, debug_cpu_i_d_n, ejtag_pcst[2:0]	Tsu20	cpu_coldreset_n rising	10	—	10	—	10	—	ms	Chapter 19, Figure 19.9 and Chapter 9, Figure 9.2	
debug_cpu_dma_n, debug_cpu_ack_n, debug_cpu_ads_n, debug_cpu_i_d_n, ejtag_pcst[2:0]	Thld20	cpu_coldreset_n rising	1	—	1	—	1	—	ns		
debug_cpu_dma_n, debug_cpu_ack_n, debug_cpu_ads_n, debug_cpu_i_d_n	Tdo20	cpu_masterclk rising	—	15	—	12	—	10	ns		
debug_cpu_dma_n, debug_cpu_ack_n, debug_cpu_ads_n, debug_cpu_i_d_n	Tdoh20	cpu_masterclk rising	1	—	1	—	1	—	ns		
JTAG Interface											
jtag_tms, jtag_tdi, jtag_trst_n	t ₅	jtag_tck rising	10	—	10	—	10	—	ns	See Figure 4 below.	
jtag_tms, jtag_tdi, jtag_trst_n	t ₆	jtag_tck rising	10	—	10	—	10	—	ns		
jtag_tdo	t ₄	jtag_tck falling	—	10	—	10	—	10	ns		

Table 6 AC Timing Characteristics - RC32334 (Part 3 of 4)

Standard EJTAG Timing — RC32334

Figure 4 represents the timing diagram for the EJTAG interface signals.

The standard JTAG connector is a 10-pin connector providing 5 signals and 5 ground pins. For Standard EJTAG, a 24-pin connector has been chosen providing 12 signals and 12 ground pins. This guarantees elimination of noise problems by incorporating signal-ground type arrangement. Refer to the RC32334 User Reference Manual for connector pinout and mechanical specifications.

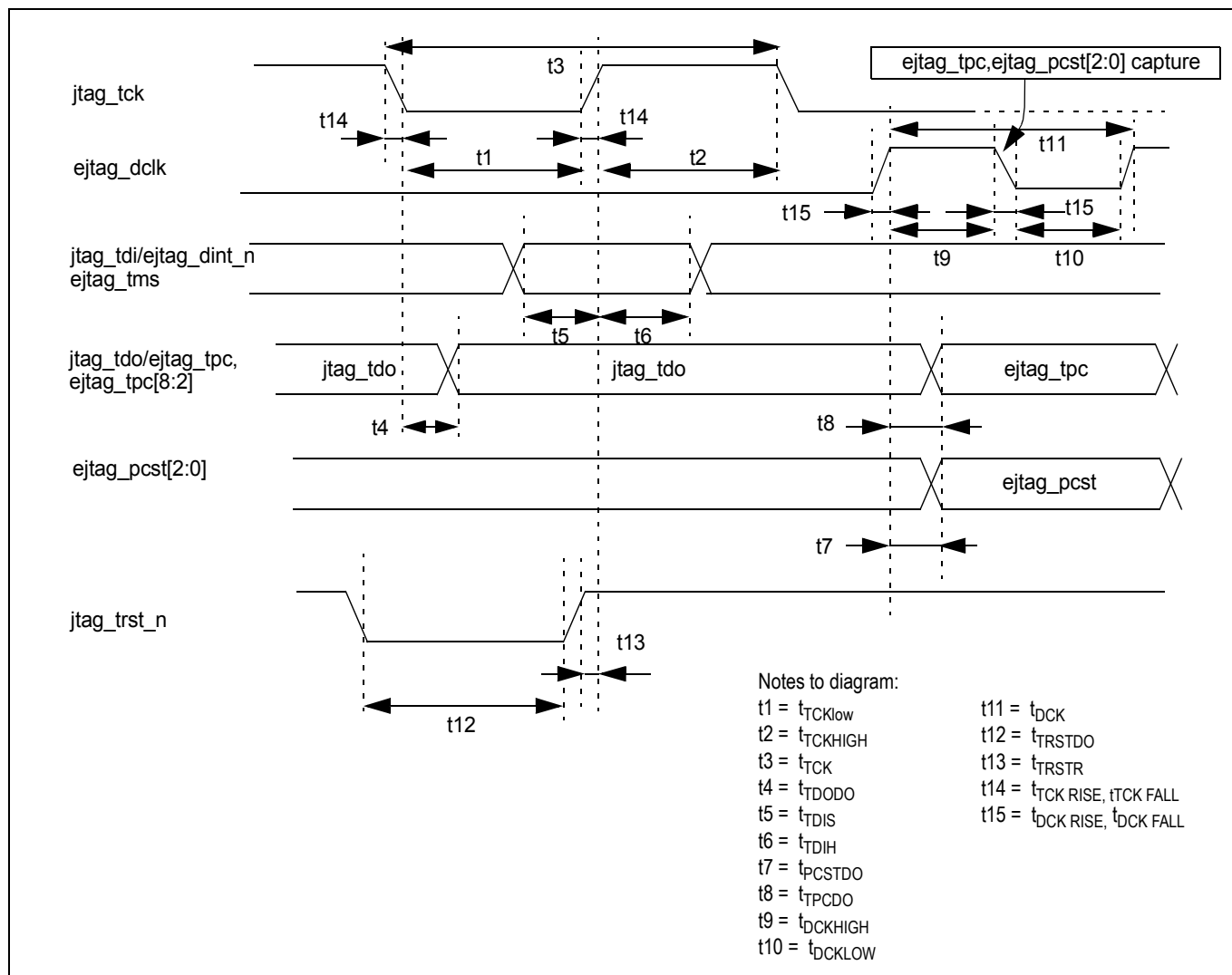
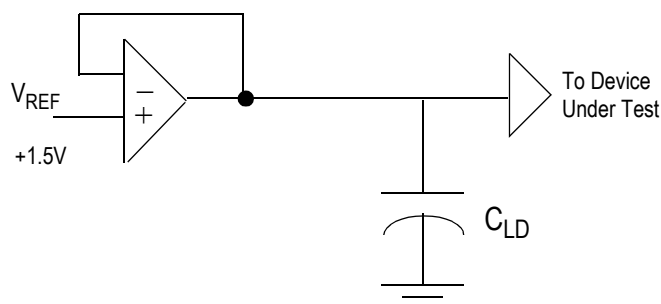


Figure 4 Standard EJTAG Timing

Output Loading for AC Testing



Signal	Cld
All High Drive Signals	50 pF
All Low Drive Signals	25 pF

Figure 5 Output Loading for AC Testing

Note: PCI pins have been correlated to PCI 2.2.

Recommended Operation Temperature and Supply Voltage

Grade	Temperature	Gnd	V _{cc} IO	V _{cc} Core	V _{cc} P
Commercial	0°C to +70°C (Ambient)	0V	3.3V±5%	3.3V±5%	3.3V±5%
Industrial	-40°C to +85°C (Ambient)	0V	3.3V±5%	3.3V±5%	3.3V±5%

Table 7 Temperature and Voltage

DC Electrical Characteristics — RC32334

Commercial Temperature Range—RC32334

(Ta = 0°C to +70°C Commercial, Ta = -40°C to +85°C Industrial, V_{cc} I/O = +3.3V±5%, V_{cc} Core = +3.3V±5%)

	Parameter	RC32334 ¹		Pin Numbers	Conditions
		Minimum	Maximum		
Input Pads	V _{IL}	—	0.8V	B14, E13, F4, K1, L2, M1, M3, M4, M14, N1-N3, P14, R2, R16	—
	V _{IH}	2.0V	—		—
LOW Drive Output Pads	V _{OL}	—	0.4V	A1, A12, A15, A16, B1, B2, B12, B15, C1-C3, C12, C13, C14, D12, D13, E1-E4, F1, F2, G1-G4, H1, H2, J1, J2, K2-K4, L1, L3, L4, P3, P14, R2, R15, R16, T16	I _{OUT} = 6mA
	V _{OH}	V _{cc} - 0.4V	—		I _{OUT} = 8mA
	V _{IL}	—	0.8V		—
	V _{IH}	2.0V	—		—
HIGH Drive Output Pads	V _{OL}	—	0.4V	A2-A4, A6-A11, A13, A14, B3, B4, B6-B11, B13, B16, C4, C6-C8, C10, C11, C15, C16, D1-D4, D6, D7, D10, D11, D14-D16, E14, E15, F3, F13-F16, G13-G16, H15, H16, J13, J14, K5, K13, K14, K16, L13-L16, M2, M13, M16, P2, P4, R1, R3, R4	I _{OUT} = 7mA
	V _{OH}	V _{cc} - 0.4V	—		I _{OUT} = 16mA
	V _{IL}	—	0.8V		—
	V _{IH}	2.0V	—		—
PCI Drive Input Pads	V _{IL}	—	—	P1, R1, R10, T2, T3	Per PCI 2.2
	V _{IH}	—	—		

Table 8 DC Electrical Characteristics - RC32334 (Part 1 of 2)

Power Curves

The following two graphs contain the simulated power curves that show power consumption at various bus frequencies.

Note: Only pipeline frequencies that are integer multiples (2x, 3x, 4x) of bus frequencies are supported.

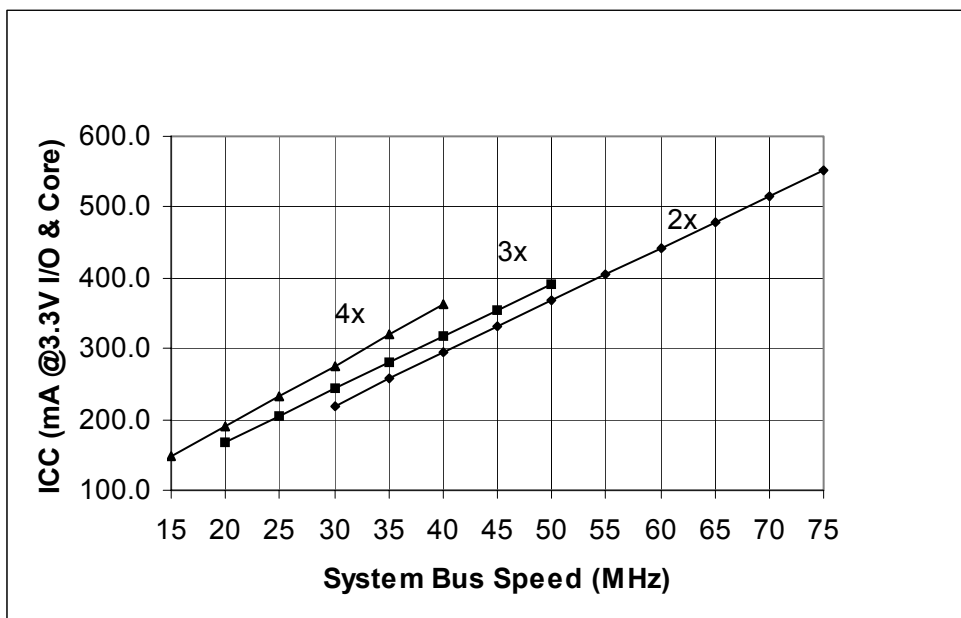


Figure 6 Typical Power Usage - RC32334

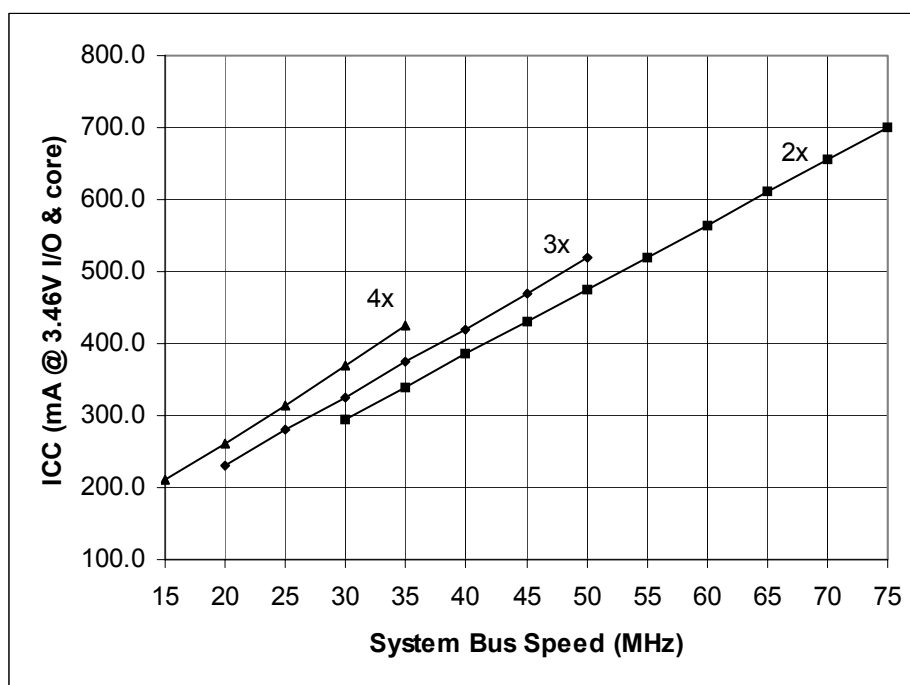


Figure 7 Maximum Power Usage - RC32334

Pin	Function	Alt	Pin	Function	Alt	Pin	Function	Alt	Pin	Function	Alt
B9	sdram_addr_12		F9	V _{ss}		K9	V _{ss}		P9	pci_cbe_n[2]	
B10	sdram_bemask_n[3]		F10	V _{ss}		K10	V _{ss}		P10	pci_devsel_n	
B11	mem_addr[16]	1	F11	V _{ss}		K11	V _{ss}		P11	pci_serr_n	
B12	mem_addr[20]	1	F12	V _{cc} IO		K12	V _{cc} IO		P12	pci_ad[14]	
B13	mem_data[11]		F13	mem_data[1]		K13	cpu_dt_r_n	2	P13	pci_ad[11]	
B14	cpu_coldreset_n		F14	mem_data[30]		K14	mem_data[6]		P14	cpu_int_n[5]	
B15	mem_addr[25]		F15	mem_data[31]		K15	mem_data[24]		P15	pci_ad[6]	
B16	mem_data[12]		F16	mem_data[0]		K16	mem_data[25]		P16	pci_ad[5]	
C1	uart_rx[0]	1	G1	dma_ready_n[0]	2	L1	ejtag_pcst[0]		R1	pci_req_n[2]	1
C2	uart_tx[0]	1	G2	mem_245_oe_n		L2	jtag_trst_n		R2	cpu_int_n[2]	
C3	uart_dtr_n[0]	1	G3	spi_mosi	2	L3	ejtag_pcst[1]	1	R3	pci_gnt_n[1]	2
C4	sdram_cs_n[0]		G4	spi_miso	2	L4	ejtag_pcst[2]	1	R4	pci_gnt_n[0]	
C5	sdram_s_n[0]		G5	V _{cc} IO		L5	V _{cc} IO		R5	pci_ad[29]	
C6	mem_addr[4]	1	G6	V _{ss}		L6	V _{ss}		R6	pci_ad[25]	
C7	mem_addr[9]	1	G7	V _{ss}		L7	V _{ss}		R7	pci_ad[22]	
C8	output_clk		G8	V _{ss}		L8	V _{ss}		R8	pci_ad[18]	
C9	mem_addr[12]		G9	V _{ss}		L9	V _{ss}		R9	pci_irdy_n	
C10	sdram_cs_n[3]		G10	V _{ss}		L10	V _{ss}		R10	pci_lock_n	
C11	mem_addr[14]	1	G11	V _{ss}		L11	V _{ss}		R11	pci_cbe_n[1]	
C12	mem_addr[18]	1	G12	V _{cc} IO		L12	V _{cc} IO		R12	pci_ad[12]	
C13	mem_addr[22]	1	G13	mem_data[3]		L13	mem_data[7]		R13	pci_ad[10]	
C14	mem_addr[24]		G14	mem_data[28]		L14	mem_data[8]		R14	pci_cbe_n[0]	
C15	mem_data[19]		G15	mem_data[29]		L15	mem_data[22]		R15	uart_tx[1]	1
C16	mem_data[13]		G16	mem_data[2]		L16	mem_data[23]		R16	cpu_int_n[4]	
D1	mem_we_n[1]		H1	spi_ss_n	1	M1	jtag_tms		T1	V _{ss}	
D2	mem_we_n[3]		H2	spi_sck	2	M2	jtag_tdo		T2	pci_req_n[1]	1
D3	mem_we_n[2]		H3	V _{cc} IO		M3	ejtag_tms		T3	pci_clk	
D4	mem_we_n[0]		H4	V _{cc} core		M4	jtag_tck		T4	pci_ad[31]	
D5	sdram_s_n[1]		H5	V _{cc} IO		M5	V _{cc} IO		T5	pci_ad[28]	
D6	mem_addr[5]	1	H6	V _{ss}		M6	V _{cc} IO		T6	pci_ad[24]	
D7	mem_addr[8]	1	H7	V _{ss}		M7	V _{cc} IO		T7	pci_ad[21]	
D8	V _{ss}		H8	V _{ss}		M8	V _{cc} IO		T8	pci_ad[17]	
D9	V _{cc} core		H9	V _{ss}		M9	V _{cc} IO		T9	pci_frame_n	
D10	sdram_cs_n[2]		H10	V _{ss}		M10	V _{cc} IO		T10	pci_stop_n	
D11	mem_addr[13]	1	H11	V _{ss}		M11	V _{cc} IO		T11	pci_par	
D12	mem_addr[17]	1	H12	V _{cc} IO		M12	V _{cc} IO		T12	pci_ad[13]	
D13	mem_addr[21]	1	H13	V _{ss} P		M13	mem_data[9]		T13	pci_ad[9]	

Table 11 RC32334 256-pin PBGA Package Pin-Out (Part 2 of 3)

RC32334 Alternate Signal Functions

Pin	Alt #1	Alt #2	Pin	Alt #1	Alt #2	Pin	Alt #1	Alt #2
A1	PIO[15]		C3	PIO[13]	C3	H2	PIO[9]	pci_eeeprom_sk
A6	sdram_addr[3]		C6	sdram_addr[4]		J1	modebit[6]	
A7	sdram_addr[7]		C7	sdram_addr[9]		J2	modebit[4]	
A8	sdram_addr[11]		C11	sdram_addr[14]		K3	modebit[3]	
A11	sdram_addr[15]		C12	modebit[8]		K4	modebit[5]	
A12	modebit[9]		C13	reset_boot_mode[1]		K13	mem_245_dt_r_n	sdram_245_dt_r_n
A16	PIO[2]	timer_gate_n[0]	D6	sdram_addr[5]		L1	modebit[0]	
B1	PIO[12]		D7	sdram_addr[8]		L3	modebit[1]	
B2	PIO[14]		D11	sdram_addr[13]		L4	modebit[2]	
B6	sdram_addr[2]		D12	modebit[7]		P2	pci_inta_n (satellite)	
B7	sdram_addr[6]		D13	reset_boot_mode[0]		P3	PIO[0]	dma_done_n[1]
B8	sdram_addr[10]		F4	sdram_wait_n		R1	pci_idsel (satellite)	
B11	sdram_addr[16]		G1	PIO[1]	dma_done_n[0]	R3	pci_eeeprom_cs (satellite)	PIO[11]
B12	reset_pci_host_mode		G3	PIO[10]	pci_eeeprom_mdo	R15	PIO[3]	
C1	PIO[6]		G4	PIO[7]	pci_eeeprom_mdi	T2	Unused (satellite)	
C2	PIO[5]		H1	PIO[8]		T16	PIO[4]	

Ordering Information

79RCXX	V	DDD	SSS	PP	
Product Type	Operating Voltage	Device Type	CPU Frequency	Package	Temp range/ Process
					Blank = Commercial Temperature (0° C to +70° C Ambient)
					I = Industrial Temperature (-40° C to +85° C Ambient)
			100 MHz		
			133MHz		
			150MHz		
		334			
				BB = 256-pin PBGA	
				BBG = 256-pin PBGA (Green package)	
	V = 3.3V ±5%				

79RC32 = 32-bit family product

Valid Combinations

79RC32V334 - 100BB, 133BB, 150BB	Commercial
79RC32V334 - 100BBG, 133BBG, 150BBG	Commercial Green
79RC32V334 - 100BBI, 133BBI, 150BBI	Industrial
79RC32V334 - 100BBGI, 133BBGI, 150BBGI	Industrial Green



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